

MSC 1000S

MSC 1000S is a peelable temporary solder resist designed to be applied to the printed circuit board prior to soldering in order to mask areas where components need to be placed after wave soldering. It is formulated to withstand fluxing and wave soldering applications. This material can be used in conjunction with fluxes whose residues do not require removal after soldering.

MSC 1000S is suitable for application by hand, template screening and pneumatic dispense equipment. It can also be applied by brush. The material is particularly suited for use on gold, silver and pre-tinned surfaces. It can also be used on copper but some discoloration, surface degradation and/or drop off in solderability may be observed.

FEATURES AND BENEFITS

- Withstands high temperatures
- Thixotropic – holds position
- Easily peelable
- Non-flammable

DIRECTIONS FOR USE

The substrate should be free of grease, oils and particulates. The MSC 1000S should be applied as a wet thickness of 2mm to ensure a suitable dry film thickness is achieved once the material has been processed. Dry the wet film at room temperature for 2 hours or in an air circulating oven for 40 minutes at 80°C. The dried MSC 1000S should be non-tacky to the touch.

Over-curing of the material should be avoided to prevent problems with the removal post soldering.

Cleaning:

MSC 1000S should be removed as soon as possible after the soldering process by peeling the film off of the substrate. An incorrect wet film thickness may cause issues with removal, especially in plated through holes.

Do not attempt to wash off MSC 1000S in a cleaning process such as solvent or water. Always remove the temporary resist prior to a cleaning process.

Storage:

It is recommended to store MSC 1000S in a dry environment at room temperature. **Shipping and storage below 5°C should be avoided to prevent irreversible separation of the material.**

Shelf Life:

Provided MSC 1000S is stored as recommended above a shelf life of 1 year can be expected.

GENERAL INFORMATION

For safe handling information on this product consult the relevant Safety Data Sheet (SDS)

Disclaimer

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. HARIMA is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product. Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

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